

Announcement and Call for Abstracts

Advanced Technology Workshop on RF and Microwave Packaging

www.imaps.org/rf

September 21 - 23, 2010

The Crowne Plaza San Diego
2270 Hotel Circle North
San Diego, CA 92108-2810

IMAPS San Diego Golf Tournament, Tuesday, September 21, 2010

**IMAPS San Diego Golf Tournament
Morning, September 21, 2010**

Workshop & Events:
Afternoon, September 21 - September 23, 2010
Tabletop Exhibits: September 22, 2010

Abstract Deadline: May 28, 2010

Organizing Committee:			
General Co-Chair Ken Kuang Torrey Hills Technologies, LLC Phone: 858-558-6666 kkuang@torreyhillstech.com	General Co-Chair Susan Trulli Raytheon Integrated Defense Systems Phone: 978- 684-8667 Susan_C_Trulli@raytheon.com	Technical Co-Chair: Sean Cahill BridgeWave Communications, Inc. Phone: 408- 567-6951 seanc@Bridgewave.com	Technical Co-Chair: Michel de Langen NXP Semiconductors Phone: +31 24 353 4481 michel.de.langen@nxp.com
Advisory Committee			
Steve Adamson, Asymtek, Inc. Ron Barnett, National Instruments Carl Edwards, Space Micro, Inc. Aicha Elshabini, University of Idaho Bill Ishii, Torrey Hills Technologies, LLC Wally Johnson, Coorstek, Inc. Iris Labadie, Kyocera America, Inc.	Charles Lin, Bridge Semiconductor, Taiwan Walt Napoleon, KL Marketing David Shields, Component Surfaces, Inc. Ziliang Wang, Nanjing Electronics Device Institute Mumtaz Bora, Peregrine Semiconductor Kai Cheng, Nanjing Guosheng Electronics Mark Eblen, Kyocera America, Inc.	Guosheng Jiang, China Central South University Lee Levine, IMAPS VP of Technology Mark Tomei, Kyocera America, Inc. David Virissimo, Coining Inc. Danny Zhu, Jiangsu Dingqi Sci. & Tech. Co. Ltd. Scott Tse, Kyocera America, Inc.	

RF and Microwave Packaging Workshop Focus:

The objective of the RF and Microwave Packaging Workshop is to provide a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who work in the area of RF and Microwave packaging technologies. This workshop enables discussion and presentation of the latest RF and Microwave technology.

Abstracts are being requested in the following areas:

Emerging Technologies	New Design/Materials	New Applications
<ul style="list-style-type: none"> 60 GHz Personal Area Network (PAN) Short Wave IR Packaging Nanopackaging 3D RF/MW New and Disruptive Technology EMI Shielding for RF/MW Packaging Wafer Level Packaging for Microwave and MMwave Applications Packaging Issues for Wide Band Gap Semiconductors SIP 	<ul style="list-style-type: none"> New Power Amplifier Design Beyond LDMOS Thermal Management New Uncooled IR Sensors Plastic RF/MW Packaging Lead Free RF MEMS 	<ul style="list-style-type: none"> Military / space Optoelectronics (night vision, thermal weapon sight, etc.) High Power Electronics Space / Extreme Environments MEMS/NEMS Biomedical Telecomm Reliability MMIC Automotive High Speed Electronics

Awards will be given in the following categories: **Best ATW Paper; Best Session Papers; and Best Student Paper.**

Those wishing to present a paper at the RF and Microwave Packaging Advanced Technology Workshop must submit a 200-300 word abstract electronically by May 28, 2010, using the on-line submittal form at: www.imaps.org/abstracts.htm.

All abstracts submitted must represent original, previously unpublished work. The abstracts should highlight the substrate advancements, materials processing/reliability, design, packaging issues and application. The submission section will aid in grouping the work within these three areas.

Student Competition sponsored by The Microelectronics Foundation:



The Microelectronics Foundation sponsors Student Paper Competitions in conjunction with all Advanced Technology Workshops (ATWs) and Conferences. Students submitting their work and identifying that "Yes, I'm a full-time student" on the abstract submission form, will automatically be considered for these competitions. The review committee will evaluate all student papers/posters and award at least one student author with a \$1,000 check at the ATW/Conference. The selected student must attend the event to present his or her work and receive the award. The Foundation will return the registration fee for the winner. The winner must pay for travel and lodging expenses.

No formal technical paper is required. A reproduction-ready 2-page extended abstract with figures and graphs included, if necessary will be required for the abstract booklet on August 6, 2010.

Accepted papers may be considered for publication in the *IMAPS Journal of Microelectronics and Electronic Packaging*.

All Speakers are required to pay a reduced registration fee and are required to attend the entire Workshop to maximize opportunities for interaction with registered attendees. All authors and attendees find that this IMAPS Workshop format is a proven forum for informal but highly effective networking between attendees and speakers.

If you are having problems with the on-line submittal form, please email Jackki Morris-Joyner at: jmorris@imaps.org or call 305-382-8433.

Official RF and Microwave Packaging Workshop site: www.imaps.org/rf